

# 2023 IEEE-EPS-IESA WORKSHOP ON SEMICONDUCTOR PACKAGING

## 30<sup>th</sup> November (Day 1) | Bengaluru

### AGENDA

TIME	AGENDA	SPEAKERS
8:00 AM - 9:30 AM	Registration	
9:30 AM - 10:30 AM	Welcome Address	<ul style="list-style-type: none"> <li>Mr. Ashok Chandak, <i>President, IESA</i></li> <li>Mr. Sam Karikalán, <i>VP of Conferences, IEEE-EPS</i></li> </ul>
	Address by Chief Guest	<ul style="list-style-type: none"> <li>Shri. Arvind Kumar, <i>Chairman - STPINEXT &amp; Director General STPI</i></li> </ul>
	Address by Guest of Honor	<ul style="list-style-type: none"> <li>Shri. BV Naidu, <i>Chairman - KDEM</i></li> <li>Shri. Abhijeet Agarwal, <i>IAS, MD MPSEDC</i></li> </ul>
	Address by Guest of Honor	<ul style="list-style-type: none"> <li>Mr. Sanjeev Kumar Gupta, <i>CEO, KDEM</i></li> </ul>
	Keynote Address	<ul style="list-style-type: none"> <li>Mr. Raghu Panicker, <i>CEO, Kaynes SemiCon</i></li> </ul>
	Vote of Thanks	<ul style="list-style-type: none"> <li>Mr. Suresh Subramanyam, <i>Founder &amp; CTO, Infinipack</i></li> </ul>
10:30 AM - 10:50 AM	Inauguration of Booth	
10:50 AM - 11:20 AM	Coffee/Tea Break	
Session 1 Title: Packaging technologies		
11:20 AM - 11:40 AM	<b>Keynote 1:</b> Semiconductor Assembly & Test: Competitive Advantage for India	<ul style="list-style-type: none"> <li>Dr. Charan Gurumurthy, <i>Senior Vice President, Tata Electronics</i></li> </ul>
11:40 AM - 12:00 PM	<b>Keynote 2:</b> Moving Design Landscape From Chip to Package	<ul style="list-style-type: none"> <li>Mr. Arun Chandrasekar, <i>Senior Principal Engineer, Intel</i></li> </ul>
12:00 PM - 12:20 PM	<b>Keynote 3:</b> Evolution of Flash Memory Packaging Solutions	<ul style="list-style-type: none"> <li>Mr. Nandha Mohanraj, <i>Director, Western Digital</i></li> </ul>
12:20 PM - 12:40 PM	<b>Keynote 4:</b> Heterogenous Integration in the AI ERA	<ul style="list-style-type: none"> <li>Mr. Sachin Patil, <i>Dy. Director Technical Program Management, AI Systems Solutions, Applied Materials</i></li> </ul>
12:40 PM - 2:10 PM	Lunch Break/ Booth Videos	
Session 2 Title: Heterogeneous Integration with IP/SoC/Chiplet		
2:10 PM - 2:30 PM	<b>Keynote 5:</b> Universal Chiplet Interconnect Express (UCIe): Building an open ecosystem of chiplets for on-package innovations	<ul style="list-style-type: none"> <li>Mr. Sridhar Muthrasanallur, <i>Sr. Principal Engineer and I/O Technologist, Intel Corporation</i></li> </ul>
2:30 PM - 2:50 PM	<b>Keynote 6:</b> Chiplet Integration Challenges and Considerations	<ul style="list-style-type: none"> <li>Mr. Sam Karikalán, <i>Sr. Manager, Broadcom</i></li> </ul>
2:50 PM - 3:10 PM	<b>Keynote 7:</b> Chiplet Architectures and 3D Heterogeneous Integration	<ul style="list-style-type: none"> <li>Mr. Priyal Shah, <i>Member of Technical Staff, Advanced Packaging, AMD</i></li> </ul>
3:10 PM - 4:10 PM	<b>Panel Session 1:</b> Challenges in IP/SoC Design for Heterogeneous Integration	<ul style="list-style-type: none"> <li>Mr. Shivraj Thakare, <i>Director IP Engineering, Intel Corporation</i></li> </ul>
		<ul style="list-style-type: none"> <li>Mr. Satya Marni, <i>Director, R&amp;D Physical Design, Synopsys In, Moderator</i></li> </ul>
		<ul style="list-style-type: none"> <li>Ms. Vijaylaxmi Khanolkar, <i>Distinguished Member Of Technical Staff, Texas Instruments</i></li> </ul>
		<ul style="list-style-type: none"> <li>Mr. Kartik Kariya, <i>Sr Director, Alphawave IP Group</i></li> </ul>
		<ul style="list-style-type: none"> <li>Mr. Rajeev Kumar, <i>Director, Platform Architect, NXP Semiconductors</i></li> </ul>
4:10 PM - 4:30 PM	Coffee/Tea Break	
Session 3 Title: Emerging optical technologies		
4:30 PM - 4:50 PM	<b>Keynote 8:</b> The Reincarnation of Interconnects in the Chiplet Era	<ul style="list-style-type: none"> <li>Mr. Shashank Gupta, <i>Technical Leader and Manager, Lightmatter</i></li> </ul>
4:50 PM - 5:10 PM	<b>Keynote 9:</b> Advanced Integration of Optical Interconnects	<ul style="list-style-type: none"> <li>Mr. Vivek Raghuraman, <i>Co-founder and CEO, Mixxtech</i></li> </ul>
5:10 PM - 5:30 PM	<b>Keynote 10:</b> Electronic-Photonic Integration on 3D System-in-Package: Architecture and Development	<ul style="list-style-type: none"> <li>Mr. Jugal Kishore, <i>System Architect, Lightspeed Photonics</i></li> </ul>
5:30 PM - 5:50 PM	<b>Keynote 11:</b> Semicon & Photonics convergence requires the scaling up of PIC (Photonics Integrated Chip) manufacturing	<ul style="list-style-type: none"> <li>Mr. Ignazio Piacentini, <i>Independent Consultant</i></li> </ul>
Session 4 Title: EDA/ Tools for Heterogeneous Integration		
5:50 PM - 6:50 PM	<b>Keynote 12:</b> Design and Simulations for Heterogeneous Integration	<ul style="list-style-type: none"> <li>Mr. Ajit Sequeria, <i>Group Director R&amp;D, Synopsys</i></li> </ul>
		<ul style="list-style-type: none"> <li>Mr. Vamsi Krishna, <i>Senior Technical Manager, Electronics, Ansys India Ltd.</i></li> </ul>
6:50 PM - 7:20 PM	Networking	
07:30 PM onwards	Banquet Speech and Cocktails/Dinner	<ul style="list-style-type: none"> <li>Mr. Veerappan V V, <i>Tessolve</i></li> <li>Mr. Ravi Mahajan, <i>Intel</i></li> </ul>

# 2023 IEEE-EPS-IESA WORKSHOP ON SEMICONDUCTOR PACKAGING

## 1<sup>st</sup> December (Day 2) | Bengaluru

### AGENDA

TIME	AGENDA	SPEAKERS
9:30 AM - 10:00 AM	Keynote 13: Packaging by the Numbers	• Mr. Raja Manickam, <i>Founder, iVP Semiconductor</i>
Session 5 Title: Emerging Technologies/ Materials		
10:00 AM - 10:20 AM	<b>Keynote 14:</b> New Frontiers in Flash Products Package Design	• Mr. Ning Ye, <i>Sr. Dir, Western Digital</i>
10:20 AM - 10:40 AM	<b>Keynote 15:</b> Advanced Materials for Semiconductor Packaging and Complex Integrated Systems	• Mr. Ravi Bhatkal, <i>MD, India, MacDermid Alpha</i>
10:40 AM - 11:00 AM	<b>Keynote 16:</b> Structural Integrity Issues Related to Package Level Interconnects: Materials Science-Informed Mechanics-Driven Approach	• Mr. Praveen Kumar, <i>Prof, Dept of Materials Engg, IISc</i>
11:00 AM - 11:20 AM	Coffee/Tea Break	
11:20 AM - 11:40 AM	<b>Keynote 17:</b> Low Temperature Low Pressure Wafer to Wafer Cu-Cu Bonding Technologies: A Giants Step Towards 3D-IC Integration	• Dr. Shiv Govind Singh, <i>Prof, Dept of EE, IIT Hyderabad</i>
11:40 AM - 12:00 PM	<b>Keynote 18:</b> Extending Moore's Law with Advanced Packaging	• Mr. Rangesh Raghavan, <i>Corporate Vice President &amp; GM, India at Lam Research</i>
12:00 PM - 12:20 PM	<b>Keynote 19:</b> The New Semiconductor and Packaging Destination	• Mr. Manas Ranjan Panda, <i>Special Secretary, E&amp;T Department, Government of Odisha</i>
12:20 PM - 12:40 PM	<b>Presentation:</b> IEEE EPS Growth Plans for India	• Ms. Kavitha Nagarajan, <i>IC Package Architect   Client Computing Group, Intel Corporation</i>
12:40 PM - 1:20 PM	Lunch Break/Booths	
Session 6 Title: OSAT/ ATMP		
1:20 PM - 1:40 PM	<b>Keynote 20:</b> India ATMP Manufacturing Workforce Opportunities	• Mr. Gokul Kumar, <i>Sr. Director, Micron</i>
1:40 PM - 2:00 PM	<b>Keynote 21:</b> Advanced Semiconductor Packaging Overview: Market & Technology Trends	• Mr. Santosh Kumar, <i>Vice President and head of semiconductor development &amp; manufacturing at Reliance</i>
2:00 PM - 2:20 PM	<b>Keynote 22:</b> Enabling Volume Testing at OSAT Keeping Test Cost, Yield and Time to Market as Priority	• Mr. Rajesh V, <i>Sr. VP, Tessolve</i>
Session 7 Title: R&D and Skilling		
2:20 PM - 2:40 PM	<b>Keynote 23:</b> Next Gen, Global-Level and Large-Scale Device, Packaging and Systems R&D and Workforce Development in India	• Prof. Rao Tummala, <i>Distinguished Chair Prof, Georgia Tech; ISM advisor</i>
2:40 PM - 3:00 PM	<b>Keynote 24:</b> Assembly and Packaging Capabilities	• Mr. Krishnan Kumar, <i>Scientist/Engineer, Semi-Conductor Laboratory</i>
3:00 PM - 3:20 PM	<b>Keynote 25:</b> SEMI Electronic Packaging Standards	• Dr. Ashwini Aggarwal, <i>Chairman, India Semiconductor Manufacturing Advisory Committee</i>
3.20PM - 3:40 PM	Networking Break	
3:40 PM - 4:40 PM	<b>Panel Session 2:</b>	• Mr. Ravi Mahajan, <i>Fellow, Intel, Moderator</i>
		• Mr. Anandaroop Bhattacharya, <i>Prof, Mech Eng, IITKGP</i>
		• Mr. Siddhartha Duttgupta, <i>Prof, EE, IITB</i>
		• Mr. Ravi Bhatkal, <i>MD, India, MacDermid Alpha</i>
		• Mr. Ashwini Aggarwal, <i>Director, Government Affairs, Applied Materials India</i>
		• Mr. Gokul Kumar, <i>Sr. Director, Micron</i>
		• Mr. Charan Gurumurthy, <i>Tata Electronics</i>
4:40 PM - 5:00 PM	Closing Remarks, Next Steps, and Future Events Plans	• Mr. Sam Karikalan / Mr. Suresh Subramanyam / Dr. Alok Nath De
5:00 PM	High Tea/Networking	
5:00 PM	Disperse - See you in 2024	